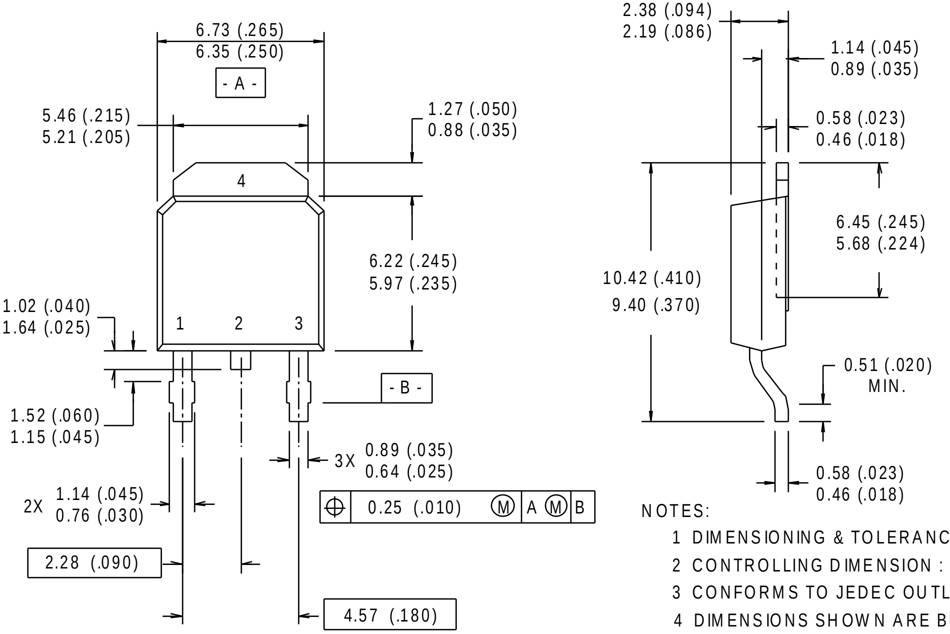
Package Outline

HEXFET TO-252AA (D-PAK) Outline

Dimensions are shown in millimeters (inches)



LEAD ASSIGNMENTS

1 - GATE
2 - DRAIN
3 - SOURCE
4 - DRAIN

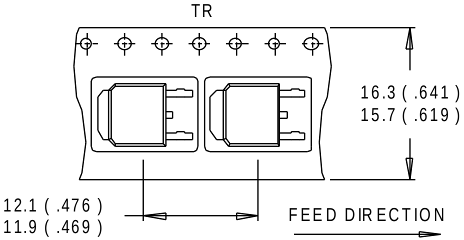
NOTES:

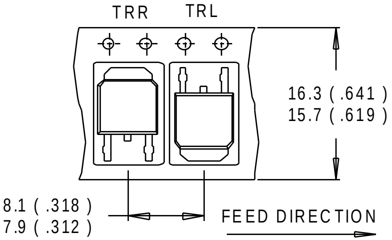
1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
2 CONTROLLING DIMENSION : INCH.
3 CONFORMS TO JEDEC OUTLINE TO-252AA.
4 DIMENSIONS SHOWN ARE BEFORE SOLDER DIP, SOLDER DIP MAX. +0.16 (.006).
5 LEADS & DRAIN CONTACT ARE PLATED: 85%/15% Sn/Pb NOMINAL.

Tape & Reel Information

HEXFET TO-252AA (D-PAK)

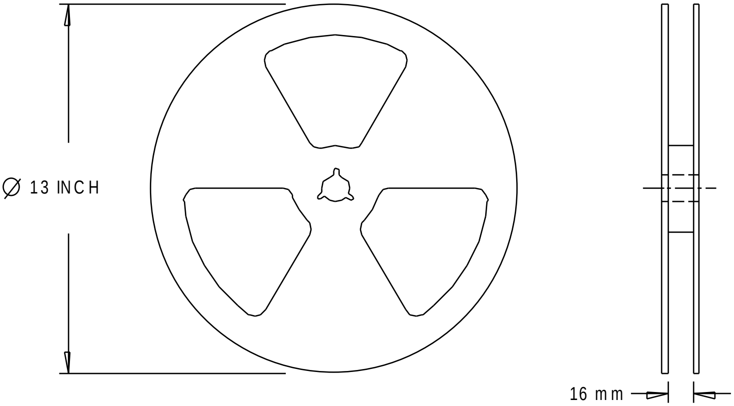
Dimensions are shown in millimeters (inches)





NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. OUTLINE CONFORMS TO EIA-481.

Part Marking Information

HEXFET TO-252AA (D-PAK)

EXAMPLE : THIS IS AN IRFR120
WITH ASSEMBLY
LOT CODE 9U1P